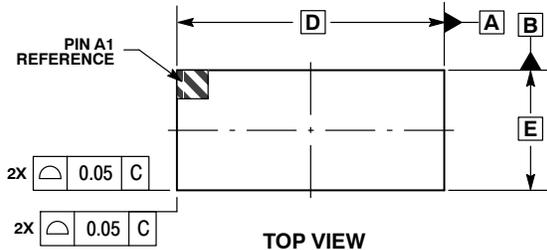




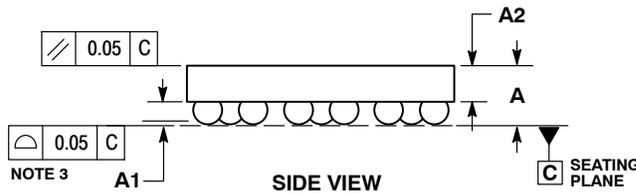
SCALE 4:1

WLCSP15, 2.96x1.33  
CASE 567BS  
ISSUE O

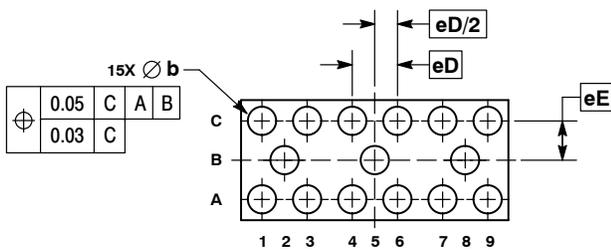
DATE 26 JUL 2010



TOP VIEW



SIDE VIEW

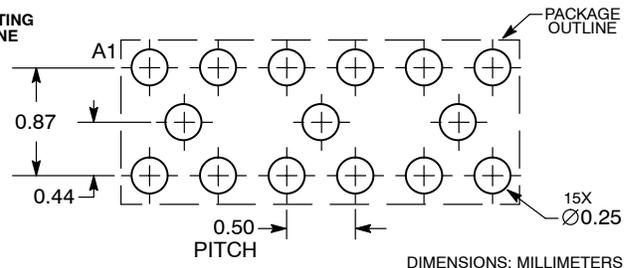


BOTTOM VIEW

- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.56	0.65
A1	0.21	0.27
A2	0.40 REF	
b	0.29	0.35
D	2.96 BSC	
E	1.33 BSC	
eD	0.50 BSC	
eE	0.435 BSC	

RECOMMENDED  
SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	WLCSP15, 2.96X1.33	PAGE 1 OF 1

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